

INTEGRATED CIRCUIT PACKAGE AND METHOD OF FABRICATING SAME**ABSTRACT OF THE DISCLOSURE**

- 5 An integrated circuit package includes a first or active substrate and a second or passive substrate. The active substrate includes at least one circuit that generates heat during circuit operation. The passive substrate does not include any heat-generating circuits, although the passive substrate may include passive, disabled or dormant circuitry. The two substrates are preferably fabricated of semiconductor material and
- 10 have substantially equal coefficients of thermal expansion. The passive substrate is thermally coupled to the active substrate preferably using a thin layer of adhesive, such as an epoxy. The passive substrate serves to thermally conduct the heat generated by the circuits of the active substrate away from the active substrate. An internal metallic heat sink may be optionally thermally coupled to the passive substrate to further aid in the
- 15 transfer of heat away from the active substrate.